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FORM HDP-1449 (Based on Form PTO-1449)  <b>PATENT AND TRADEMARK OFFICE</b> <b>INFORMATION DISCLOSURE CITATION</b> (Use several sheets if necessary)  Sheet 1 of 3	ATTORNEY DOCKET NO.	SERIAL NO.
	6550-000013	09/114,665
	APPLICANT Thomas R. Bieler et al.	
	FILING DATE	GROUP
	July 13, 1998	1742

U.S. PATENT DOCUMENTS						
Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date
1.	<i>BE</i>	3,481,795	12/1969	Lane	136/237	
2.	<i>BE</i>	4,248,905	2/1981	Harvey	427/11	
3.	<i>BE</i>	4,358,884	11/1982	Harvey et al.	29/408.18	
4.	<i>BE</i>	4,506,822	3/1985	Hammersand et al.	278/200	
5.	<i>BE</i>	5,066,544	11/1991	Betrabet et al.	428/647	
6.	<i>BE</i>	5,094,700	3/1992	Sekhar	148/538	
7.	<i>BE</i>	5,344,607	9/1994	Gonya et al.	420/562	
8.	<i>BE</i>	5,429,689	7/1995	Shangguan et al.	148/400	
9.	<i>BE</i>	5,527,628	6/1996	Anderson et al.	428/647	

FOREIGN PATENT DOCUMENTS							
Ref. Desig.	Examiner's Initials	Document Number	Date	Country	Class/ Subclass	Translation	
						Yes	No
1.							

OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)		
Ref. Desig.	Examiner's Initials	
1.	<i>BE</i>	Attarwala, A.I. et al., "Confirmation of Creep and Fatigue Damage in Pb/Sn Solder Joints," <i>J. Electron. Packag.</i> 114:109-111 (1992)
2.	<i>BE</i>	Betrabet, H.S. et al., "Processing Dispersion-Strengthened Sn-Pb Solders To Achieve Microstructural Refinement And Stability," <i>Script Metall.</i> 25:2323-2328 (1991)

Examiner: <i>Sikya JP</i>	Date Considered: <i>11/22/99</i>
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OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)		
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3.	<i>CE</i>	Betrabet, H.S. et al., "Towards Increased Fatigue Resistance In Sn-Pb Solders By Dispersion Strengthening," <i>Proc. Conf. NEPCON.</i> , West Anaheim, CA, pp. 1276-1277 (1992)
4.	<i>CE</i>	Clough, R.B. et al., "Preparation And Properties Of Reflowed Paste And Bulk Composite Solder," <i>Proc. Conf. NEPCON.</i> , West Anaheim, CA, pp. 1256-1265 (1992)
5.	<i>CE</i>	Frear, D.R. et al., "Thermal Fatigue In Solder Joints," <i>JOM</i> , pgs. 18-22 (June, 1988)
6.	<i>CE</i>	Ho, C.T. et al., "Carbon fiber reinforced tin-lead alloy as a low thermal expansion solder preform," <i>J. Mater. Res.</i> 5(6):1266-1270 (1990)
7.	<i>CE</i>	Jin, S., "Solder Materials Issues In High-Density Interconnection And Packaging," <i>Final Program ASM-TMS Materials Week '96</i> , ASM International and The Minerals, Metals & Materials Society, Cincinnati, Ohio, pp. 116 (1996)
8.	<i>CE</i>	Kuo, C.G. et al., "Fatigue Deformation Of In-Situ Composite Solders," <i>1st Int'l. Conf. Microstructures and Mechanical Properties of Aging Materials</i> , ed. P.K. Liaw, R. Viswanathm, K.L. Murty, E.P. Simonen and D.R. Frear, The Minerals Metals & Materials Society, TMS, Warrendale, PA, pp. 417-423 (1993)
9.	<i>CE</i>	Kuo, C.G. et al., "Tensile And Creep Properties Of In-Situ Composite Solders," <i>1st Int'l. Conf. Microstructures and Mechanical Properties of Aging Materials</i> , ed. P.K. Liaw, R. Viswanathm, K.L. Murty, E.P. Simonen and D.R. Frear, The Minerals Metals & Materials Society, TMS, Warrendale, PA, pp. 409-415 (1993)
10.	<i>CE</i>	Lau, J.H. et al., "Solder Joint Fatigue In Surface Mount Technology: State of the Art," <i>Solid State Tech.</i> pp. 91-104 (1985)
11.	<i>CE</i>	Marshall, J.L. et al., "Composite Solders," <i>IEEE Trans. Comp. Hybrids Manuf. Tech.</i> 14(4):698-702 (1991)
12.	<i>CE</i>	Marshall, J.L. et al., "Microcharacterization Of Composite Solders," <i>Proc. Conf. NEPCON.</i> , West Anaheim, CA, pp. 1278-1283 (1992)
13.	<i>CE</i>	McCormack, M. et al., "The Design and Properties of New, Pb-Free Solder Alloys," <i>Proc. IEEE/CPMT Int'l Electronics Manufacturing Technology Symp.</i> pp. 7-14 (1994)

Examiner: <i>S. Kyin Jr</i>	Date Considered: <i>11/22/99</i>
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OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)		
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14.	<i>BE</i>	McCormack, M. et al., "Enhanced Solder Alloy Performance by Magnetic Dispersions," <i>IEEE Trans. Comp. Hybrids Manuf. Tech.-Part A</i> 17(3):452-457 (1994)
15.	<i>BE</i>	Pinizzotto, R.F. et al., "Microstructural Development In Composite Solders Caused By Long Time, High Temperature Annealing," <i>Proc. Conf. NEPCON.</i> , West Anaheim, CA, pp. 1284-1298 (1992)
16.	<i>BE</i>	Sastry, S.M.L., et al., "Microstructures And Mechanical Properties Of In-Situ Composite Solders," <i>Proc. Conf. NEPCON</i> , West Anaheim, CA, pp. 1266-1275 (1992)
17.	<i>BE</i>	Shangguan, D. et al., "Evaluation of Lead-Free Eutectic Sn-Ag Solder For Automotive Electronics Packaging Applications," <i>Proc. IEEE/CPMT Int'l Electronics Manufacturing Technology Symp.</i> , pp. 25-37 (1994)
18.	<i>BE</i>	Shine, M.C. et al., "Fatigue of Solder Joints in Surface Mount Devices," <i>ASTM STP</i> 942:588-610 (1988)
19.	<i>BE</i>	Tien, J.K. et al., "Creep-Fatigue Interactions in Solders," <i>IEEE Trans. Comp. Hybrids Manuf. Tech.</i> 12(4):502-505 (1989)
20.	<i>BE</i>	Wasynczuk, J.A. et al., "Shear Creep Of Cu <sub>6</sub> Sn <sub>5</sub> /Sn-Pb Eutectic Composites," <i>Proc. Conf. NEPCON.</i> , West Anaheim, CA, pp. 1245-1255 (1992)
21.	<i>BE</i>	Weinbel, R.C. et al., "Creep-fatigue interaction in eutectic lead-tin solder alloy," <i>J. Mater. Sci.</i> 22:3901-3906 (1987)

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 GROUP 10

Examiner: <i>Sikym</i>	Date Considered: <i>11/22/98</i>
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